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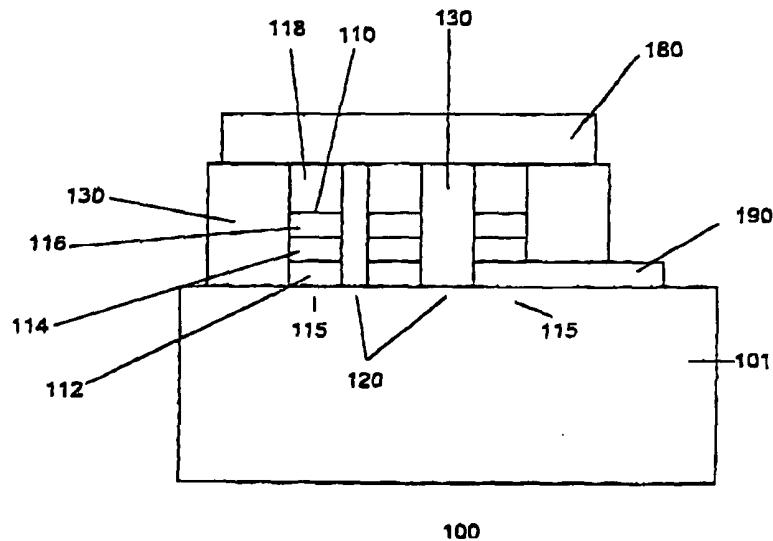
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(54) Title: ENCAPSULATION OF A DEVICE



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(57) Abstract: An encapsulation for an electrical device (100) is disclosed. A cap support (130) is provided in the non-active regions (120) of the device (100) to prevent the package from contacting the active components (110) of the device due to mechanical stress induced in the package.

Abstract

An encapsulation for an electrical device is disclosed. A cap support is provided in the non-active regions of the device to prevent the package from 5 contacting the active components of the device due to mechanical stress induced in the package.